



BES2700H

Brief Datasheet

Ultra-low Power Bluetooth Audio Platform

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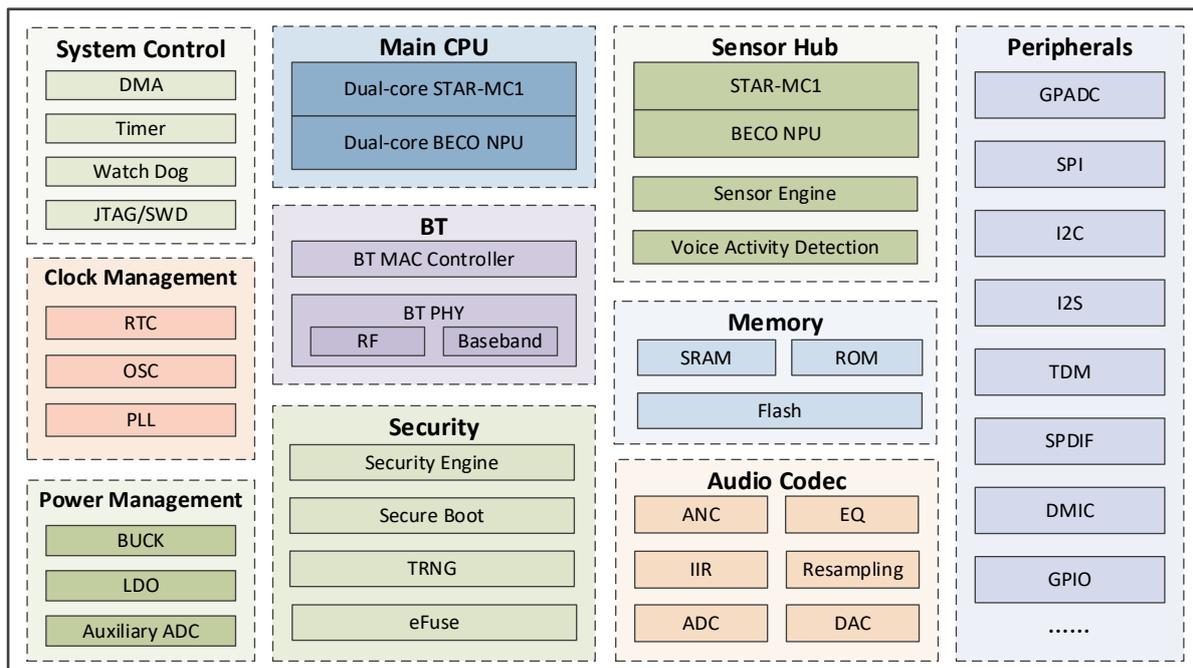
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1 General Description

The BES2700H is an ultra-low power Bluetooth audio SoC. The platform incorporates a high performance CPU subsystem comprising a dual-core STAR-MC1 processor with a dual-core BECO NPU, a BES proprietary coprocessor for advance signal processing and NN workloads, and a sensor hub subsystem comprising a STAR-MC1 processor with a BECO NPU, RAM/ROM, serial flash for software features and product customization, as well as a variety of interfaces.

The platform integrates a dual-mode Bluetooth 5.4 subsystem for both Bluetooth classic and LE audio, and an audio codec subsystem supporting voice activity detection. The highly integrated design minimizes external components, reduces BOM costs and offers a cost-effective Bluetooth audio solution.



System Block Diagram

1.1 Applications

- Smart headphones/headsets with adaptive ANC
- Bluetooth speakers with LE audio
- Other portable audio devices

1.2 Features & Specifications*

CPU Subsystem	Dual-core STAR-MC1
Sensor Hub Subsystem	STAR-MC1
	Sensor engine
Memory and Storage	Shared 2.2 MB SRAM
	Flash in package
	boot ROM
Bluetooth Subsystem	Dual-mode BT 5.4 with LE audio
Audio & Voice Features	2x DACs
	5x ADCs
Peripheral Interfaces	GPADC/eMMC/SPI/I2C/UART/I2S/TDM/SPDIF/DMIC/PWM/GPIO.....
Package	219-pin BGA

* The content in the table is subject to change without notice.